

ABSTRACT OF THE DISCLOSURE

A polishing composition comprising polymer particles and inorganic particles in an aqueous medium, wherein the inorganic particles have an average particle size of from 5 to 170 nm, and wherein an average particle size D_p (nm) of said polymer particles and an average particle size D_i (nm) of said inorganic particles satisfy the following formula (1): $D_p \leq D_i + 50$ nm (1); a polishing process for a substrate to be polished comprising polishing the substrate to be polished with the polishing composition as defined above; and a process for improving a rate for polishing a substrate to be polished with the polishing composition as defined above. The polishing composition of the present invention can be favorably used in polishing the substrate for precision parts, including semiconductor substrates; substrates for magnetic recording media such as magnetic discs, optical discs and opto-magnetic discs; photomask substrates; glass for liquid crystals; optical lenses; optical mirrors; optical prisms; and the like.